



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/ITS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET

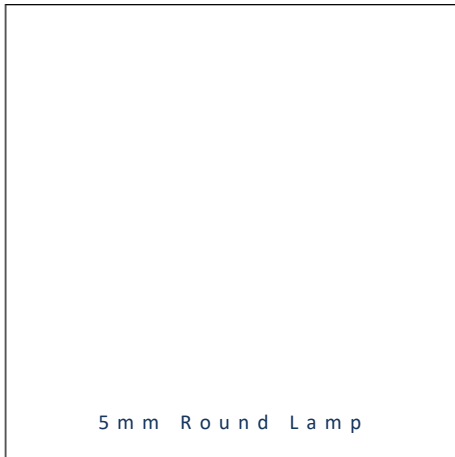


- ▶ PTH/THT Lamp
- ▶ 5mm Round 8.7t
- ▶ Infrared IR (880nm)

NOF37L41



Release Date: 16 April 2023 Version: A1.0



5 m m R o u n d L a m p

5mm Round Lamp

RoHS
Compliant



FEATURES:

- **Package:** PTH/THT 5mm Round 8.7t LED Lamp
- **Forward Current:** 20mA
- **Forward Voltage (typ.):** 1.3V
- **Radiant Intensity (typ.):** 25mW/sr@20mA
- **Colour:** Infrared IR
- **Peak Wavelength (typ.):** 880nm
- **Viewing Angle:** 16°
- **Materials:**
 - Die: GaAlAs
 - Resin: Epoxy (Water Clear)
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **Grouping Parameters:**
 - Forward voltage
 - Luminous intensity
 - Peak wavelength
- **Soldering Methods:** Hand; Soldering Heat (DIP)
- **MSL Level:** acc. to JEDEC Level 3
- **Packing:** 500pcs/bulk

APPLICATIONS:

- Remote Control
- Smoke Detector
- Photo Detector
- Burglar Alarm
- Computer I/O Peripheral
- Automatic Control System
- Industrial Application

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Continuous Forward Current	I _F	60	mA
Peak Forward Current Width 10us Duty 1%	I _{FP}	1	A
Reverse Current @5V	I _R	100	μA
Reverse Voltage	V _R	5	V
Power Dissipation	P _D	100	mW
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

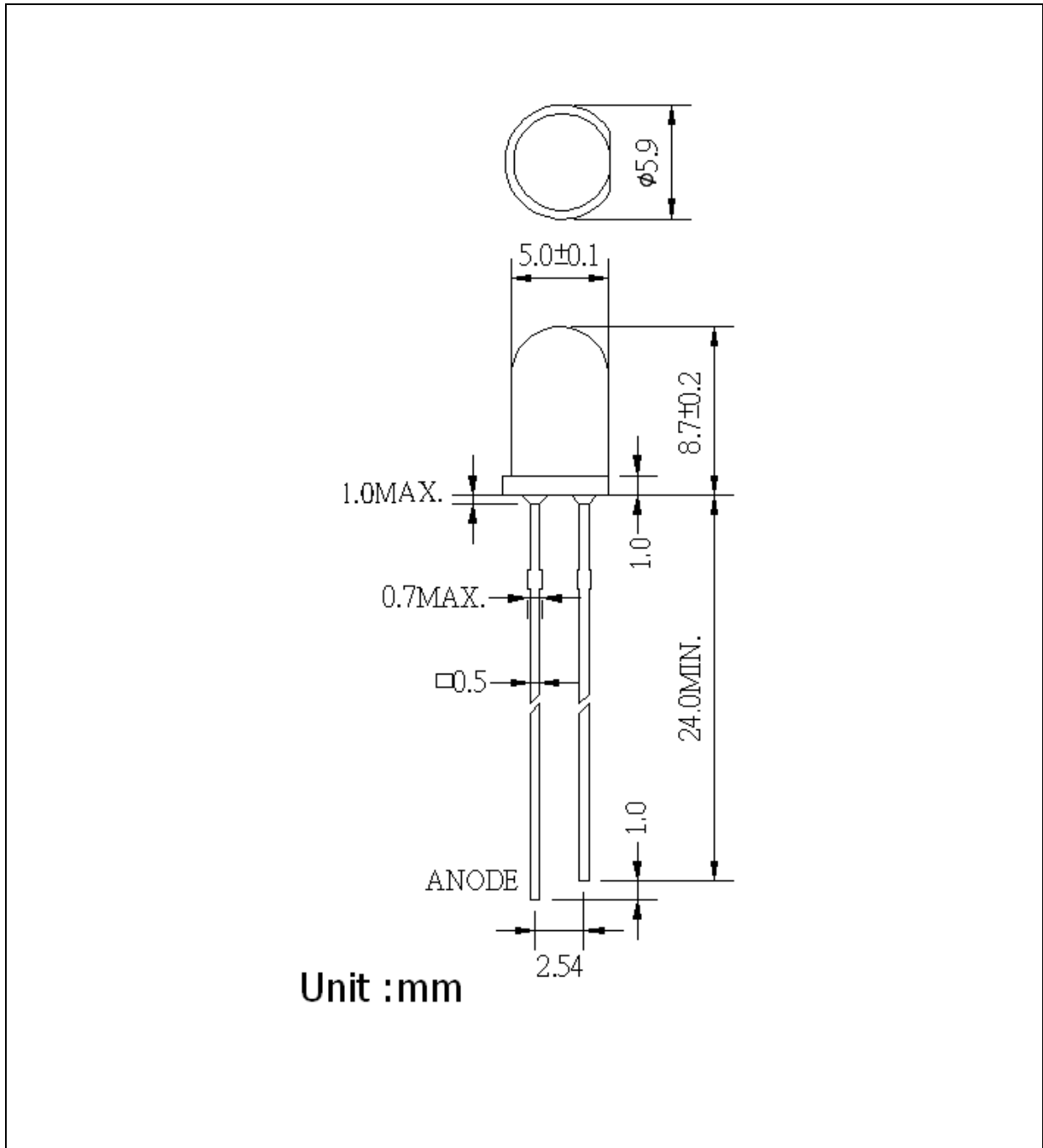
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V _F	---	1.3	1.6	V	I _F =20mA
Radiant Intensity	I _e	20	25	---	mW/sr	I _F =20mA
Peak Wavelength	λ _P	---	880	---	nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ	---	70	---	nm	I _F =20mA
Viewing Angle	2θ _{1/2}	---	16	---	deg	I _F =20mA
Rise Time	T _R	---	---	500	nS	I _F =50mA
Fall Time	T _F	---	---	500	nS	I _F =50mA

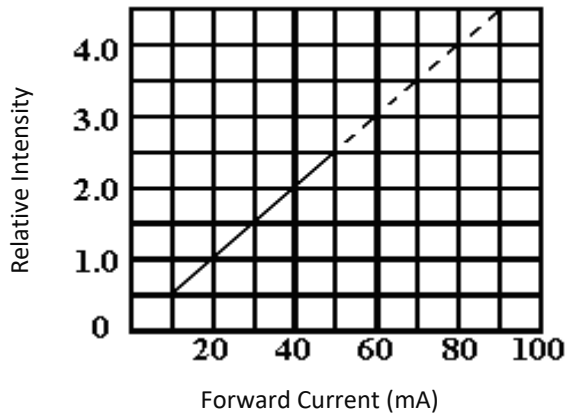
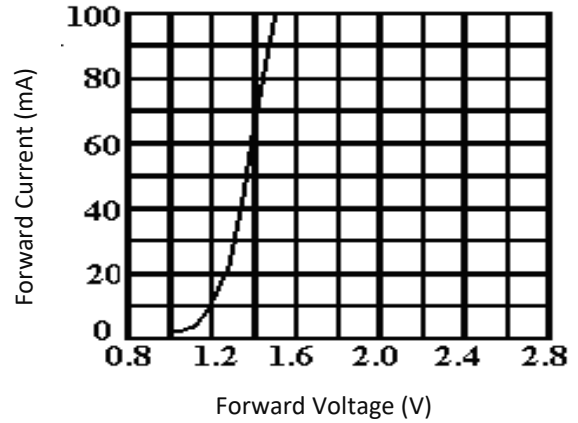
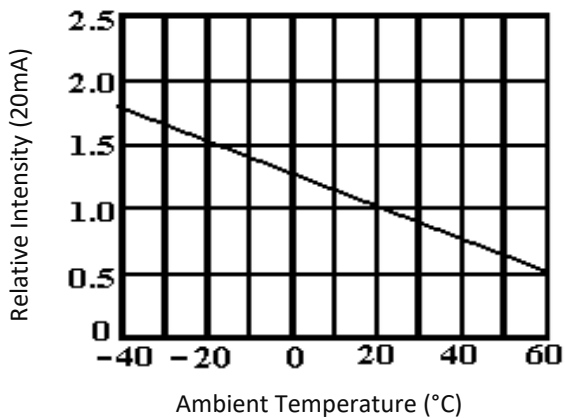
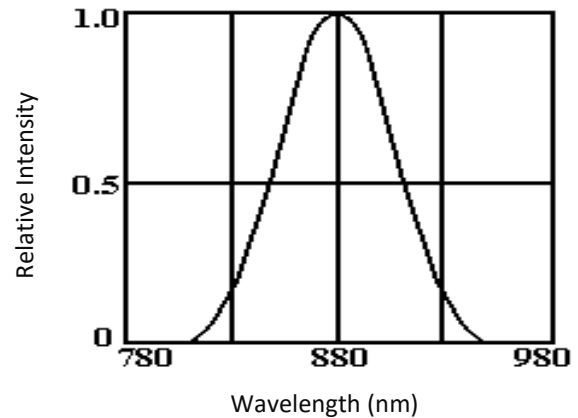
1. Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2θ_{1/2}) ±5%

OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance ± 0.2 mm, unless otherwise noted.

ELECTRO-OPTICAL CHARACTERISTICS:
Relative Intensity v.s. Forward Current

Forward Current v.s. Forward Voltage

Relative Intensity v.s. Temperature

Relative Intensity v.s. Wavelength


RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds \pm 1 sec.

Soldering Heat (DIP):

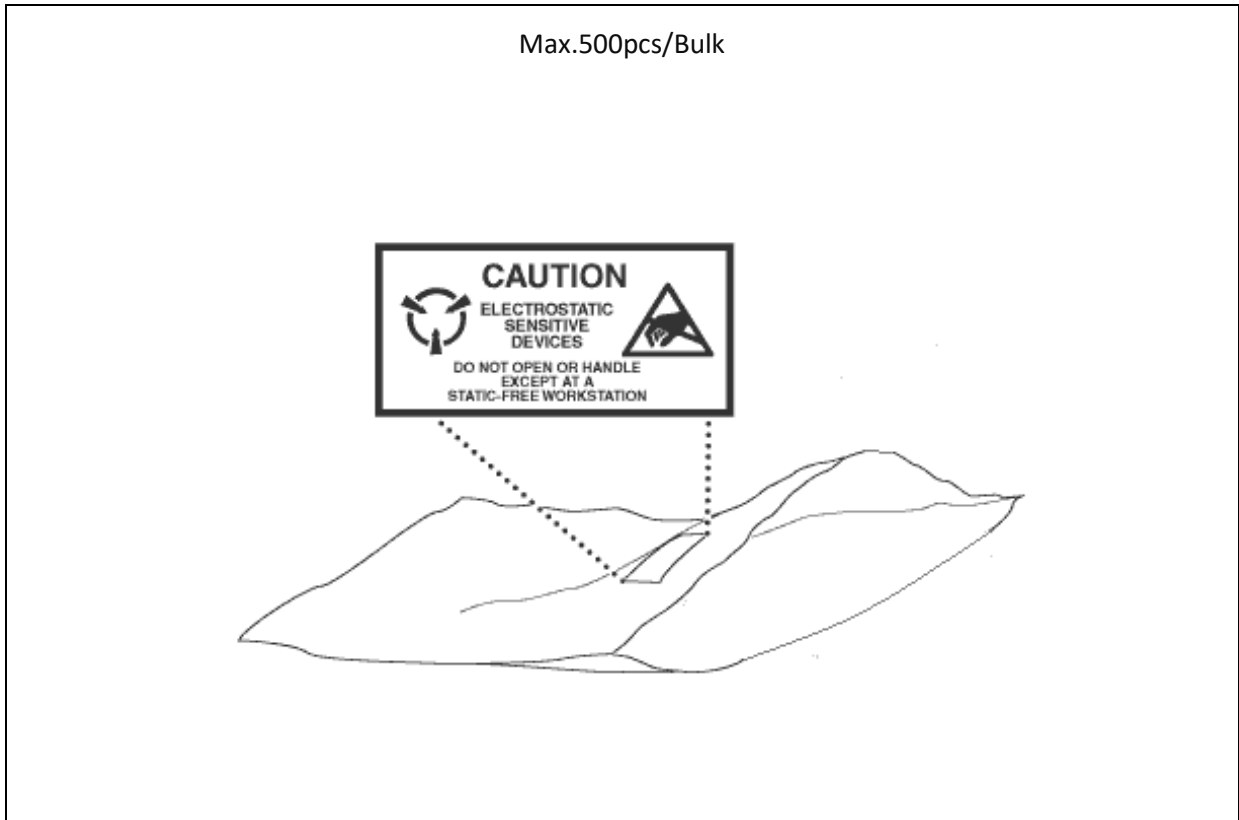


Note:

1. Maximum reflow soldering: 1 time.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	16/04/2023	Datasheet set-up.